



Field of Application
SMT-Stencil cleaning within automatic
cleaning equipment

Customer benefits

Efficient removal of solder paste and SMT-adhesive from stencils grants repeatable and stable cleaning process which helps to achieve high-quality printing results. The waterbased formulation combines high flashpoint and work safety level and helps to eliminate flammable solvents from within the production area

Please consider approvals of equipment manufacturer!

Technical Data

Appearance / Consistency: Colorless to slightly yellow, clear

Application: Ready-to-use

Density at 20°C: 0,981 +/- 0,005 g/cm³

pH-value Neutral

Boiling point / boiling range: >100°C

System: Waterbased

Flashpoint: None

Operations temperature: Room temperature

Reliable cleaning results with: Leaded, lead-free, no-clean solder pastes
SMT-adhesives

Shelf life (month) 36

Storage conditions Ideal in original packaging at 10-25°C

Transportation: Non-DG

Packaging: 5 L blue plastic can
20 L green plastic can

Application notes:

The waterbased, pH-neutral cleaning media efficiently removes leaded, lead-free, no-clean solder pastes and SMT-adhesives from SMT-stencils within automatic cleaning equipment. **Etimol SW 25 RAN** shows excellent dissolving properties that grant stable and high quality cleaning results and shows excellent rinsability with itself and DI-water.

The cleaning media is used straight at room temperature and put within the cleaning tank of the automatic equipment.

Consider approvals of equipment manufacturer!

Consider compatibility of SMT-stencil adhesive!